



Type Document	Product Specification	Revised /Edition	C
Date Issued	2010/01/23	Data Revised	2012/02/03
Subject: JS-1285 JS-1285-T JS-1285-T(G) JS-1295 JS-2285 JS-2295 JS-2295R Pitch 1.25mm SMT(Double Row & Single Row)Series Wire to Board Connector			Issued By: Engineering Dept.

*This specification is referred to 1.25mm SMT
 (Double Row ; Single Row) series wire to board connector.
 本規格書內容係提供 1.25 mm SMT(雙排 ; 單排)系列產品相關參考，
 其用途為電線端相接於電路板端連接器*

-INDEX-

- 1.0 Product Name/Part Number & Drawing Number.
(產品名稱 / 產品型號及圖面型號)
- 2.0 Construction/Dimensions/Material & Surface Finish.
(材質以及表面鍍層)
- 3.0 Characteristic.
(產品特性)
- 4.0 Specimen.
(樣本圖示)
- 5.0 Applicable Standards.
(適用規範)
- 6.0 Mechanical Performance.
(機械性能)
- 7.0 Electrical Performance.
(電氣性能)
- 8.0 Environmental Performance.
(環境性能)
- 9.0 Insertion Force (I.F.) & Withdrawal Force (R.F.) for user reference
(Housing 對 Wafer 插入力與拔出力參考規格)
- 10.0 **Caution (注意事項)**
- 11.0 Remark (備註)

REV. (版次)	Revision Record (改版變更原因)	Date(日期)	EC No
B	鹽水噴霧週期以電鍍方式區隔為 8 小時與48 小時	2011/05/05	EC2011-05-008
C	1增加耐久性 及溫升 2.刪除硫化氫 3.修正(EIA-364) 參考規範 4. 增列額定電壓 5 增加10.0 產品使用 注意事項	2012/02/03	EC2012-02-008



喬訊電子工業股份有限公司

CHYAO SHIUNN ELECTRONIC INDUSTRIAL LTD.

7FL., NO.17, LANE 3, SEC.1 CHUNG CHENG EAST RD.,
TAMSHUI, TAIPEI, TAIWAN, R.O.C.

TEL: 886-2-2629-9955 (REP) FAX: 886-2-2626-6677

http://www.chyaoshiunn.com.tw E-mail:cs@chyaoshiunn.com.tw



Certificate Number PB 2014
ISO 9002

Type Document	Product Specification	Revised /Edition	C
Date Issued	2010/01/23	Data Revised	2012/02/03
Subject: JS-1285 JS-1285-T JS-1285-T(G) JS-1295 JS-2285 JS-2295 JS-2295R Pitch 1.25mm SMT(Double Row & Single Row)Series Wire to Board Connector			Issued By: Engineering Dept.

1.0 Product Name/Part Number & Drawing Number(產品名稱 / 產品型號及圖面型號): Note: (xx) The number of the circuits.

Product Name(產品名稱)	Part Numbe(零件型號)	Drawing Number(圖面型號)
Crimp Terminal 鍍壓端子	JS-1285-T	(Stamping before Plated 先衝壓後電鍍) JS-1285-T
	JS-1285-T(G)	JS-1285-T(G)
Housing 電線端連接器	Single Row 單排	JS-1285-XX JS-1285-XX
	Double Row 雙排	JS-2285-XX JS-2285-XX
Wafer 電路板端連接器	Single Row ; Right Angle 單排 ; 臥式	JS-1295-XX/(G)/(NM) JS-1295-XX/(G)/(NM)
	Double Row ; Straight 雙排 ; 直立式	JS-2295-XX JS-2295-XX
	Double Row ; Right Angle 雙排 ; 臥式	JS-2295R-XX JS-2295R-XX

2.0 Construction/Dimensions/Material & Surface Finish(材質以及表面鍍層):

Part Name(零件名稱)	Material(材質)	Surface Finish(表面鍍層)		
Crimp Terminal	JS-1285-T	Tin-Plated		
	JS-1285-T(G)	Gold Plated		
Housing	PBT for 2~19 Circuit	UL 94V-0 ; Color : Black		
	Nylon 66 for 20~30Circuit			
Wafer	Single Row	Contacts (導體)	Brass	Gold / Matte-Tin/ Tin Plated
	Row	Solder Nail (固定片)	Brass	Tin Plated
		Base (膠座)	Nylon PA46 or Nylon PA9T	UL 94V-0
	Double Row	Contacts (導體)	Copper Alloy	0.8u" Au over Plated ,30u" under all over
		Shell (金屬外殼)	Copper Alloy	Tin Plated
		Base (膠座)	Nylon PA46	UL 94V-0 ; Color : Black



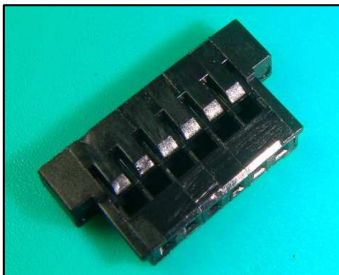
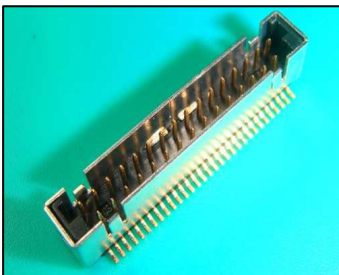
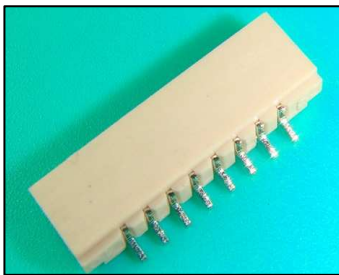
3.0 Characteristic(產品特性):

Item(項目)	Standard(標準規範)	
3.1 額定電流 Rated Current	1A AC/DC With AWG #28 is applied (相對適用於美國電線規格 UL1007 AWG #28)	
3.2 額定電壓 Rated Voltage	200 V AC/DC	
3.3 Ambient Temperature Range 環境與操作溫度範圍	(操作使用溫度範圍) Operating Temp.: -40°C~+85°C Including 30°C Terminal Temperature Rise at rated Current , (包括定額電流內, 端子所產生 30°C 以下溫昇) (置存於環境當中溫度與濕度範圍) Non - Operating Temp. : -40°C~+85°C ; 90% R.H. Max	
3.4 Applicable Wire 適用電線型	(金屬導體型號) Conductor Construction Size: AWG #28~#32	
3.5 Applicable Printed Circuit Board Layout 適用電路板佈局設計	3.5.1 SMT Layout: 1.25 ± 0.05 mm per Pitch 表面黏著焊錫點間距	
	3.5.2 (Single- Row) SMT Layout	SMT Layout: 0.7X1.45±0.10 mm for Pin Post 導體焊錫點面積
		SMT Layout: 1.35X1.60±0.10 mm for Solder Nail 固定片焊錫點面積
	3.5.3 (Double- Row) SMT Layout	SMT Layout: 0.40X1.45±0.10 mm for Pin Post 導體焊錫點面積
		SMT Layout: 1.35X1.60±0.10 mm for Solder Nail 固定片焊錫點面積



Type Document	Product Specification	Revised /Edition	C
Date Issued	2010/01/23	Data Revised	2012/02/03
Subject: JS-1285 JS-1285-T JS-1285-T(G) JS-1295 JS-2285 JS-2295 JS-2295R Pitch 1.25mm SMT(Double Row & Single Row)Series Wire to Board Connector			Issued By: Engineering Dept.

4.0 Specimen(樣本圖示) :

Part Name / Part Number / Picture or Photograph 零件名稱 / 零件型號 / 樣本圖示			
Crimp Terminal JS-1285-T JS-1285-TG			
Housing Double Row JS-2285-XX		Wafer Single Row JS-1285-XX	
Wafer Double Row Straight JS-2295-XX		Wafer Single Row Right Angle JS-1295-XX	

5.0 Applicable Standards(適用規範):

MIL-STD-202 Testing method for electronic connectors used in electronic equipment.

連接器使用於電器產品，所適用之 MIL-STD-202 測試規範

ANSI/EIA 364 ; EIA/ECA 364 Testing method for electrical connectors.

電子連接器，所適用之 ANSI/EIA 364 ; EIA/ECA 364 測試規範

6.0 Mechanical Performance(機械性能):

Item(項目)	Test Condition(測試條件)	Requirement(規格)
6.1 Insertion & Withdrawal Force 插入力與拔出力	Insert and withdrawal with connectors at the speed rate of 25.4±3mm/minute. (Excluding Plastic or Metal Lock 不包含膠座或金屬般卡棒結合) Housing 連同端子與 Wafer 兩端互配，以每一分鐘 25.4 ± 3 mm 的速率，作 插入與拔出往返測試 (EIA/ECA 364-13D)	Refer to 9.1 Table1. 參照第 9.1 項 表格 1



Type Document	Product Specification	Revised /Edition	C
Date Issued	2010/01/23	Data Revised	2012/02/03
Subject: JS-1285 JS-1285-T JS-1285-T(G) JS-1295 JS-2285 JS-2295 JS-2295R Pitch 1.25mm SMT(Double Row & Single Row)Series Wire to Board Connector			Issued By: Engineering Dept.

Item(項目)	Test Condition(測試條件)	Requirement(規格)
6.2 Wire Pullout Force(Axial) 電線脫離端子包覆之拔出力(軸向)	Pull out the cable from with contact terminal at the speed rate of 25 .4± 3 mm/minute. 對端子所包覆電線，施以每一分鐘 25 .4± 3 mm 速率之軸向拔出力 (EIA 364-08B)	AWG#28 size wire 1.4kgf/Min.(13.72N 牛頓)
		AWG#30 size wire 1.0kgf/Min.(9.8N 牛頓)
		AWG#32 size wire 0.6kgf/Min.(5.88N 牛頓)
6.3 Crimp Terminal Retention Force (in Housing) 端子與 Housing 之間拔出力	Axial pullout force on the terminal in the housing at the speed rate of 25.4 ± 3 mm per minute. (EIA/ECA 364-29C) 對於已經存在於 Housing 當中 Terminal，施以每一分鐘 25.4 ± 3 mm 速率之軸向拔出力	單一接觸點 Per Contact 最小容許值 0.6kgf/Min.
6.4 Pin Retention Force (in Base) Pin 針與膠座之間拔出力	Axial pullout force on the pin in the base at the speed rate of 25.4 ± 3 mm per minute. (EIA/ECA 364-29C) 對於已經存在於膠座當中Pin針，施以每一分鐘25.4 ± 3mm速率之軸向拔出力	單一接觸點 Per Contact 最小容許值 0.3kgf/Min.

7.0 Electrical Performance(電氣性能) :

Item(項目)	Test Condition(測試條件)	Requirement(規格)
7.1 (Low –Signal Level) Contact Resistance (低階信號) 接觸阻抗	A maximum voltage of 20mV and a maximum current of 10mA are applied to the Mate connector. 對組合狀態下連接器，於其兩端施以最大測試電壓 20mV 以及最大測試電流 10mA (EIA/ECA 364-23C) (Does not include wire resistance 不包含電線阻抗)	Contact Resistance: 40 milliohms Max. 最大容許值. 40 m 歐姆
7.2 Insulation Resistance 絕緣阻抗	Apply 500V D/C for 1 minute between adjacent contacts to measure the insulation resistance. 對相鄰兩接觸導體，於一分鐘時間內施予 500V D/C 電壓，並量測其間絕緣阻抗值 (EIA 364-21C)	Insulation Resistance: Initial 100 megohms Min 最初容許值. 100 M 歐姆
7.3 Withstanding Voltage 耐電壓	Apply 500V A/C (rms) for 1 minute and the leakage current shall not exceed 0.5mA to the adjacent terminal and ground of the Mate connectors. 對組合狀態下連接器，於其相鄰兩導體末端各施以電壓 500V A/C (實效值) 時間 1 分鐘，且漏電流必須小於 0.5mA(毫安培) (EIA 364-20C)	No breakdown or flashover. 無損毀或者產生火花



Type Document	Product Specification	Revised /Edition	C
Date Issued	2010/01/23	Data Revised	2012/02/03
Subject: JS-1285 JS-1285-T JS-1285-T(G) JS-1295 JS-2285 JS-2295 JS-2295R Pitch 1.25mm SMT(Double Row & Single Row)Series Wire to Board Connector			Issued By: Engineering Dept.

8.0 Environmental Performance(環境性能) :

Item(項目)	Test Condition(測試條件)	Requirement(規格)
8.1 Durability 耐久性	Mate Connectors up 50 Cycles at a Maximun rate of 10 cycles Per minute prior to environmental test (EIA/ECA 364-09C) 以組合狀態下連接器且未經環境測試，依每分鐘內進行 10 次嵌入與拔出之最大速率，連續 50 次嵌入與拔出往返測試	(After the test) Contact resistance : 經耐久性試驗後接觸阻抗： 80 mΩ Max
8.2 Temperature Rise (Via Current Cycling) 溫度上昇 (經由電流循環操作)	Mate connector . measure the temperature rise of contact when the maximum rated current is passed 以組合狀態下連接器，通過最大容許電流量測其導體溫度上昇值 (EIA 364-70B Conditions 1 . Method 1)	Mate connectors Temperature Rise: +30°C/Max. 組合狀態下之連接器溫度 上昇最大容許值+30°C
8.3 Vibration 耐振動	A mated connector shall be mounted on a printed Circuit board and subjected to a vibration test of the following conditions. During the test, test current continuity shall be checked. After the test, contact resistance shall be measured. 以組合狀態下連接器焊接於電路板作為試驗樣品,依照隨附如下規格要求,進行耐振動試驗，試驗過程中確認是否產生不連續電流(斷電)現象，並於試驗過後量測其接觸阻抗。 (EIA/ECA 364-28E-Condition I) Frequency(頻率) : 10~55~10 Hz/minute. Amplitude (振幅) : 1.5 mm P-P Direction (方向) :1. Axis of up and down.上下軸向(Y 軸) 2. Axis of right the left. 左右軸向(X 軸) 3. Axis of front and back.前後軸向(Z 軸) Period(週期) : 2 hours for each direction. (每一個軸向持續 2 小時)	Initial Contact Resistance : 40 milliohms Max. 接觸阻抗最初容許值: 40m 歐姆 (After the test) Contact Resistance: 40 milliohms Max. 經耐振動試驗後接觸阻抗： 最大容許值 40m 歐姆 No discontinuity current is longer than 1 microsecond. 電流中斷現象， 時間不可多於1微秒



Type Document	Product Specification	Revised /Edition	C
Date Issued	2010/01/23	Data Revised	2012/02/03
Subject: JS-1285 JS-1285-T JS-1285-T(G) JS-1295 JS-2285 JS-2295 JS-2295R Pitch 1.25mm SMT(Double Row & Single Row)Series Wire to Board Connector			Issued By: Engineering Dept.

Item(項目)	Test Condition(測試條件)	Requirement(規格)
8.4 Humidity (Steady State) 恆溫恆濕	<p>A mated connector shall be placed in a humidity chamber of the following conditions. After the test, the contact resistance, the insulation resistance and the dielectric withstanding voltage shall be measured.</p> <p>(EIA 364-31B Conditions III . Method A)</p> <p>以組合狀態下連接器放置於恆定溫度的濕氣空間，依照隨附如下規格要求，進行恆溫恆濕試驗，並於試驗過後量測其接觸阻抗、絕緣阻抗、以及耐電壓測試。</p> <p>Temperature(溫度) : 40±2°C. Relative Humidity(相對濕度) : 90%~95% (RH). Period(週期) : 96 hours continuously. (持續 96 小時)</p>	<p>(After the test)</p> <p>Contact Resistance: 80 milliohms Max. 經恆溫恆濕試驗後接觸阻抗： 最大容許值. 80m 歐姆</p> <p>(After the test)</p> <p>Insulation Resistance : 50 Megohms Min. 經恆溫恆濕試驗後絕緣阻抗： 最小容許值. 50 M 歐姆</p> <p>經恆溫恆濕試驗後耐電壓： (After the test) Withstanding Voltage: 500V A/C for 1 minute</p>
8.5 Thermal Shock 冷熱衝擊	<p>A mated connector shall be subjected to a thermal shock test of the following conditions. After the test, the contact resistance, the insulation resistance and the dielectric withstanding voltage shall be measured.</p> <p>(EIA/ECA 364-32D Conditions I . Method A)</p> <p>以組合狀態下連接器作為試驗樣品，依照隨附如下規格要求，進行冷熱衝擊試驗，並於試驗過後量測其接觸阻抗、絕緣阻抗、以及耐電壓測試。</p> <p>One Cycle Consists Of: -55 +0/-3°C for 30 minutes. → Room Temp.5 minutes 85+3/-0°C for 30 minutes. → Room Temp.5 minutes</p> <p>Total Cycles: 5 Cycles.</p> <p>以-55+0/-3°C溫度持續 30 分鐘，經室溫 5 分鐘，而後再以 85+3/-0°C溫度持續 30 分鐘，再經室溫 5 分鐘，構成一次冷熱循環，總計循環次數 5 次。</p>	<p>Same as paragraph 8.4 同 8.4 章節</p>



Type Document	Product Specification	Revised /Edition	C
Date Issued	2010/01/23	Data Revised	2012/02/03
Subject: JS-1285 JS-1285-T JS-1285-T(G) JS-1295 JS-2285 JS-2295 JS-2295R Pitch 1.25mm SMT(Double Row & Single Row)Series Wire to Board Connector			Issued By: Engineering Dept.

Item(項目)	Test Condition(測試條件)	Requirement(規格)
8.6 Thermal Aging 高溫老化試驗	A mated connector shall be placed in a heat oven of the following conditions. After the test, contact resistance shall be measured. 以組合狀態下連接器放置於加熱烤箱當中，依照隨附如下規格要求，進行高溫老化試驗，並於試驗過後量測其接觸阻抗。 (EIA 364-17B Conditions III . Method A) Temperature(溫度) : 85±2℃. Period(週期): 96 hours continuously . (持續 96 小時)	Initial Contact Resistance : 40 milliohms Max. 接觸阻抗最初容許值:40m 歐姆 (After the test) Contact Resistance : 80 milliohms Max. . 經試高溫老化試驗後接觸阻抗 : 最大容許值. 80m 歐姆
8.7 Salt Spray 鹽水噴霧	A mated connector shall be subjected to a Salt Spray test of the following conditions. After the test , the specimen shall be washed with running water and dried naturally before the measurement of contact resistance. 以組合狀態下連接器作為試驗樣品，依照隨附如下規格要求，進行鹽水噴霧試驗，試驗過後將樣品用清水沖洗並經過自然風乾，而後量測其接觸阻抗。 (EIA 364-26B Conditions B) Density(鹽水密度): 5 % in weight. Temperature(溫度): 35±2℃. Period(週期): Terminal or contact (Stamping after tin plated for 8 hours) ; Terminal or contact (Stamping before tin plated for 48 hours) 端子或導體(先電鍍後沖壓 8 小時) ; 端子或導體 (先沖壓後電鍍 48 小時)	Initial Contact Resistance : 40 milliohms Max. 接觸阻抗最初容許值:40m 歐姆 (After the test) Contact Resistance: 80 milliohms Max. 經鹽水噴霧試驗後接觸阻抗 : 最大容許值. 80m 歐姆
8.8 Solder Ability 焊錫性	Fluxed soldering section of header shall be dipped in solder of the following conditions. 將連接器 pin 針基板嵌入端，接觸熱溶狀錫料，依照隨附如下規格要求，進行焊錫性試驗 (EIA 364-52B) Solder Temperature (焊錫溫度) : 245 ± 5℃. Immersion Period (沉浸週期) : 3±0.5 Seconds (操作方式) : 零件焊錫位置，距離導體以及固定片末端 0.5mm Method : 0.5mm From Terminal Tip and Solder Tab Tip	Solder entirely 95% of immersed area must show no voids or pinholes. 焊錫覆蓋面積必須達到 95% , 而且不能產生氣孔或空隙

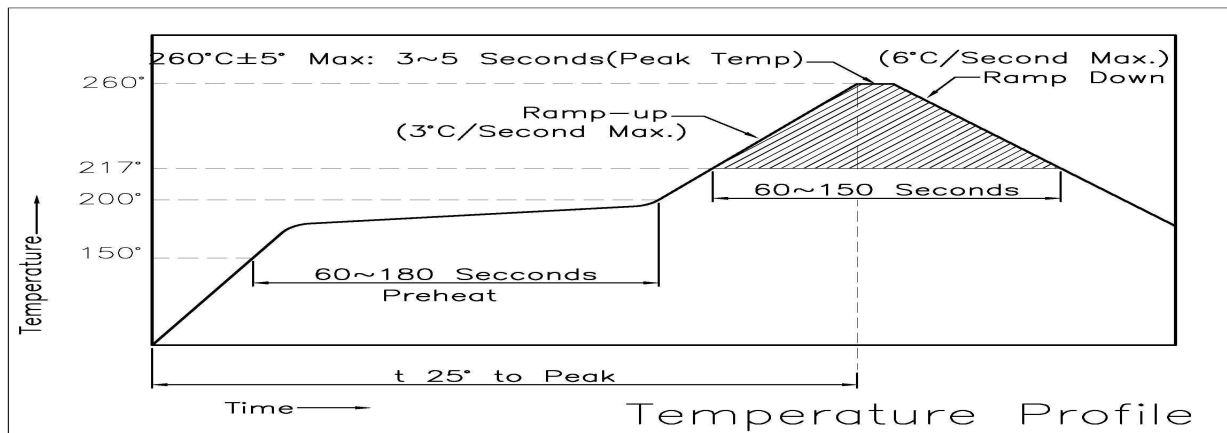


Type Document	Product Specification	Revised /Edition	C
Date Issued	2010/01/23	Data Revised	2012/02/03
Subject: JS-1285 JS-1285-T JS-1285-T(G) JS-1295 JS-2285 JS-2295 JS-2295R Pitch 1.25mm SMT(Double Row & Single Row)Series Wire to Board Connector			Issued By: Engineering Dept.

Item(項目)	Test Condition(測試條件)	Requirement(規格)
8.9	Resistance To Soldering Heat 焊錫耐熱性 By reflow soldering 迴焊適用溫度範圍 : Refer to Temperature Profile 請參考 8.9.1 溫度曲線圖 By soldering iron 手工烙鐵焊錫適用溫度範圍 : 350 ± 5°C 3±0.5 Seconds. (操作方式) : 零件焊錫位置 , 距離導體以及固定片末端 0.5mm Method : 0.5mm From Terminal Tip and Solder Tab Tip (EIA/ECA 364-56C Procedure 3. Conditions A)	No deformation or damage. 不可有變形或損壞

Notes : Flowing Mixed Gas (EIA 364-65A) shall be conduct by Customer request 混合流動氣體測試依照客戶需求

8.9.1 Temperature Profile(溫度曲線圖) :



9.0 Tables & Attachments

9.1 Table 1. Insertion Force (I.F.) & Withdrawal Force (R.F.) for user reference:

No. Of Circuits 極數	(JS-2295 Series) AT INITIAL 首次嵌入與拔出(初始值)		No. Of Circuits 極數	(JS-2295 Series) AT INITIAL 首次嵌入與拔出(初始值)	
	I.F. (MAX) 嵌入力	R.F. (MIN) 拔出力		I.F. (MAX) 嵌入力	R.F. (MIN) 拔出力
	13	3.9		0.39	21
15	4.5	0.45	31	9.3	0.93
17	5.1	0.51	41	12.3	1.23
19	5.7	0.57			

Unit: kg/f



喬訊電子工業股份有限公司
CHYAO SHIUNN ELECTRONIC INDUSTRIAL LTD.
 7FL., NO.17, LANE 3, SEC.1 CHUNG CHENG EAST RD.,
 TAMSHUI, TAIPEI, TAIWAN, R.O.C.
 TEL: 886-2-2629-9955 (REP) FAX: 886-2-2626-6677



http://www.chyaochiunn.com.tw E-mail:cs@chyaochiunn.com.tw

Type Document	Product Specification	Revised /Edition	C
Date Issued	2010/01/23	Data Revised	2012/02/03
Subject: JS-1285 JS-1285-T JS-1285-T(G) JS-1295 JS-2285 JS-2295 JS-2295R Pitch 1.25mm SMT(Double Row & Single Row)Series Wire to Board Connector			Issued By: Engineering Dept.

No. Of Circuits 極數	(JS-1295 Series) AT INITIAL 首次嵌入與拔出(初始值)		No. Of Circuits 極數	(JS-1295 Series) AT INITIAL 首次嵌入與拔出(初始值)	
	I.F. (MAX) 嵌入力	R.F. (MIN) 拔出力		I.F. (MAX) 嵌入力	R.F. (MIN) 拔出力
	02	0.6		0.06	13
03	0.9	0.09	14	4.2	0.42
04	1.2	0.12	15	4.5	0.45
05	1.5	0.15	16	4.8	0.48
06	1.8	0.18	17	5.1	0.51
07	2.1	0.21	18	5.4	0.54
08	2.4	0.24	19	5.7	0.57
09	2.7	0.27	20	6.0	0.60
10	3.0	0.30	25	7.5	0.75
11	3.3	0.33	30	9.0	0.90
12	3.6	0.36			

Unit: kg/f

10.0 Caution (注意事項) : Parts are made of hydrophilic Polyamide 46 and apt to absorb moisture. Once the vacuum-packing unpacked, please keep parts in the environment of **temperature < 30°C/ humidity < 60% RH**, and send to re-flowing **within 24 hours** to prevent parts blistered or deformed during soldering.

PA46塑料因具親水之特性，故採用真空包裝以減少吸濕受潮。真空包裝經拆封應避免曝露於溫度高於30°C，濕度高於60% RH的環境中，並在拆封24小時內全數使用完畢，以防止後續迴焊製程產生起泡泡變形現象。

11.0 Remark(備註) : Any change or revision for the product specification will not be announced in advance. Please contact our sales representative for the latest information.
 有關規格書內容經變更或改版，如未能夠及時發佈與通知，煩請連絡我司業務人員以提供產品最新資訊

Reviewed: S.M.Chang **Approved:** Peter Chang **Verified:** Indiana Huang